

## N-CHANNEL ENHANCEMENT MODE VERTICAL D-MOS TRANSISTOR

N-channel enhancement mode vertical D-MOS transistor in a TO-18 envelope. Designed primarily as a line current interrupter in telephone sets, it can also be applied in other applications such as in relays, line and high-speed transformer drivers etc.

### Features

- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown.

### QUICK REFERENCE DATA

Drain-source voltage	V <sub>DS</sub>	max.	200 V
Drain current (DC)	I <sub>D</sub>	max.	350 mA
Total power dissipation up to $T_{case} = 25^\circ\text{C}$	P <sub>tot</sub>	max.	1.5 W
Drain-source ON-resistance $I_D = 400 \text{ mA}; V_{GS} = 10 \text{ V}$	R <sub>DSon</sub>	typ. max.	4.5 $\Omega$ 6.0 $\Omega$
Transfer admittance $I_D = 400 \text{ mA}; V_{DS} = 25 \text{ V}$	Y <sub>fs</sub>	min. typ.	140 mS 350 mS

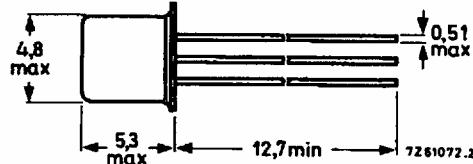
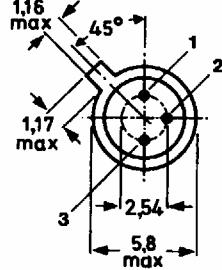
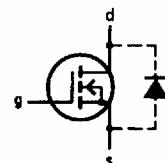
### MECHANICAL DATA

Fig. 1 TO-18.

Dimensions in mm

#### Pinning

- 1 = source  
2 = gate  
3 = drain



**RATINGS**

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Drain-source voltage	$V_{DS}$	max.	200 V
Gate-source voltage (open drain)	$\pm V_{GSO}$	max.	20 V
Drain current (DC)	$I_D$	max.	350 mA
Drain current (peak)	$I_{DM}$	max.	1.4 A
Total power dissipation up to $T_{amb} = 25^\circ\text{C}$ $T_{case} = 25^\circ\text{C}$	$P_{tot}$	max.	0.4 W
Storage temperature range	$T_{stg}$	—	-55 to +150 °C
Junction temperature	$T_j$	max.	150 °C

**THERMAL RESISTANCE**

From junction to ambient	$R_{th j-a}$	=	310 K/W
From junction to case	$R_{th j-c}$	=	83 K/W

**CHARACTERISTICS** $T_j = 25^\circ\text{C}$  unless otherwise specified

Drain-source breakdown voltage

 $I_D = 10 \mu\text{A}; V_{GS} = 0$  $V_{(BR)DSS}$  min. 200 V

Drain-source leakage current

 $V_{DS} = 60 \text{ V}; V_{GS} = 0$  $I_{DSS}$  max. 200 nA $V_{DS} = 200 \text{ V}; V_{GS} = 0$  $I_{DSS}$  typ. 100 nA $I_{DSS}$  max. 10  $\mu\text{A}$ 

Gate-source leakage current

 $V_{GS} = 20 \text{ V}; V_{DS} = 0$  $I_{GSS}$  max. 100 nA

Gate threshold voltage

 $I_D = 1 \text{ mA}; V_{DS} = V_{GS}$  $V_{GS(th)}$  min. 0.8 V $V_{GS(th)}$  max. 2.8 V

Drain-source ON-resistance

 $I_D = 400 \text{ mA}; V_{GS} = 10 \text{ V}$  $R_{DSon}$  typ. 4.5  $\Omega$  $R_{DSon}$  max. 6.0  $\Omega$ 

Transfer admittance

 $I_D = 400 \text{ mA}; V_{DS} = 25 \text{ V}$  $|Y_{fs}|$  min. 140 mS $|Y_{fs}|$  typ. 350 mSInput capacitance at  $f = 1 \text{ MHz}$ ; $V_{DS} = 25 \text{ V}; V_{GS} = 0$  $C_{iss}$  typ. 45 pF $C_{iss}$  max. 60 pFOutput capacitance at  $f = 1 \text{ MHz}$ ; $V_{DS} = 25 \text{ V}; V_{GS} = 0$  $C_{oss}$  typ. 15 pF $C_{oss}$  max. 25 pFFeedback capacitance at  $f = 1 \text{ MHz}$ ; $V_{DS} = 25 \text{ V}; V_{GS} = 0$  $C_{rss}$  typ. 3.5 pF $C_{rss}$  max. 10 pF

Switching times (see Figs 2 and 3)

 $I_D = 300 \text{ mA}; V_{DD} = 50 \text{ V}; V_{GS} = 0 \text{ to } 10 \text{ V}$  $t_{on}$  typ. 5 ns $t_{on}$  max. 15 ns $t_{off}$  typ. 15 ns $t_{off}$  max. 25 ns

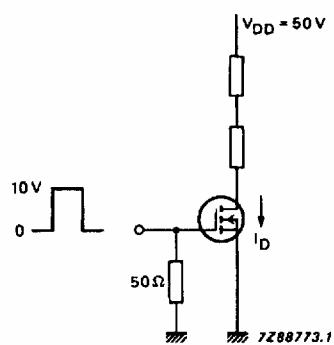


Fig. 2 Switching time test circuit.

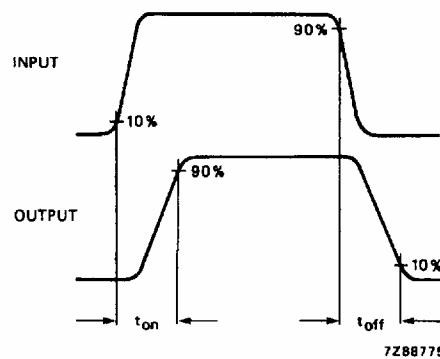


Fig. 3 Input and output waveforms.